Lattice Semiconductor Corporation - M5LV-512/160-10YI Datasheet

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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	512
Number of Gates	-
Number of I/O	160
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m5lv-512-160-10yi

Table 2. MACH 5 Speed Grades

Device	Speed Grade[1]						
	-5	-6	-7	-10	-12	-15	-20
M5-128[2]			C	C, I	C, I	C, I	I
M5-128/1	C		C, I	C, I	C, I	C, I	I
M5LV-128	C		C,I	C, I	C, I	I	
M5-192/1	C		C, I	C, I	C, I	C, I	I
M5-256[2]			C	C, I	C, I	C, I	I
M5-256/1	C		C, I	C, I	C, I	C, I	I
M5LV-256	C		C, I	C, I	C, I	I	
M5-320		C	C, I	C, I	C, I	C, I	I
M5LV-320		C	C, I	C, I	C, I	C, I	I
M5-384		C	C, I	C, I	C, I	C, I	I
M5LV-384		C	C, I	C, I	C, I	C, I	I
M5-512		C	C, I	C, I	C, I	C, I	I
M5LV-512		C	C, I	C, I	C, I	C, I	I

Note:

1. *C = Commercial grade, I = Industrial grade*
2. */1 version recommended for new designs*

With Lattice's unique hierarchical architecture, the MACH 5 family provides densities up to 512 macrocells to support full system logic integration. Extensive routing resources ensure pinout retention as well as high utilization. It is ideal for PAL® block device integration and a wide range of other applications including high-speed computing, low-power applications, communications, and embedded control. At each macrocell density point, Lattice offers several I/O and package options to meet a wide range of design needs (Table 3).

Table 3. MACH 5 Package and I/O Options [1]

	M5-128/1 M5LV-128		M5-192/1	M5-256/1 M5LV-256		M5-320 M5LV-320		M5-384 M5LV-384		M5-512 M5LV-512	
Supply Voltage	**5**	**3.3**	**5**	**5**	**3.3**	**5**	**3.3**	**5**	**3.3**	**5**	**3.3**
100-pin TQFP	68	68, 74	68	68	68*, 74						
100-pin PQFP	68	68*	68*	68*	68						
144-pin TQFP		104			104						
144-pin PQFP	104	104*	104*	104*	104*						
160-pin PQFP	120	120	120	120	120	120*	120	120*	120	120*	120
208-pin PQFP				160	160	160	160	160	160	160	160
240-pin PQFP						184*	184*	184*	184*	184*	184*
256-ball BGA						192	192*	192*	192*	192*	192*
352-ball BGA										256	256

Note:

1. *The I/O options indicated with a "*" are obsolete, please contact factory for more information.*

Advanced power management options allow designers to incrementally reduce power while maintaining the level of performance needed for today's complex designs. I/O safety features allow for mixed-voltage design,

and both the 3.3-V and the 5-V device versions are in-system programmable through an IEEE 1149.1 Test Access Port (TAP) interface.

FUNCTIONAL DESCRIPTION

The MACH 5 architecture consists of PAL blocks connected by two levels of interconnect. The **block interconnect** provides routing among 4 PAL blocks. This grouping of PAL blocks joined by the block interconnect is called a **segment**. The second level of interconnect, the **segment interconnect**, ties all of the segments together. The only logic difference between any two MACH 5 devices is the number of segments. Therefore, once a designer is familiar with one device, consistent performance can be expected across the entire family. All devices have four clock pins available which can also be used as logic inputs.

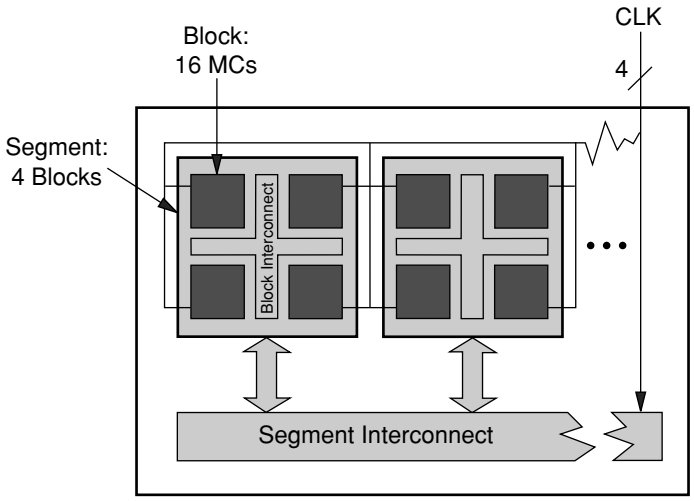

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Figure 1. MACH 5 Block Diagram

The MACH 5 PAL blocks consist of the elements listed below (Figure 2). While each PAL block resembles an independent PAL device, it has superior control and logic generation capabilities.

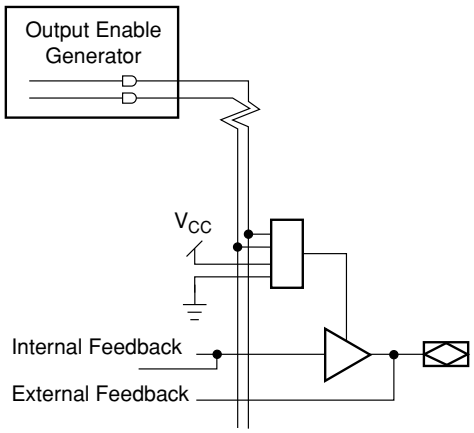
- I/O cells
- Product-term array and Logic Allocator
- Macrocells
- Register control generator
- Output enable generator

I/O Cells

The I/Os associated with each PAL block have a path directly back to that PAL block called **local feedback**. If the I/O is used in another PAL block, the **interconnect feeder** assigns a **block interconnect** line to that signal. The interconnect feeder acts as an input switch matrix. The block and segment interconnects provide connections between any two signals in a device. The **block feeder** assigns block interconnect lines and local feedback lines to the PAL block inputs.

OE Generator

There is one output enable (OE) generator per PAL block that generates two product-term driven output enables. Each I/O cell is simply an output buffer. Each I/O cell within the PAL block can choose to be permanently enabled, permanently disabled, or choose one of the two product term output enables per PAL block (Figure 6).



20446G-006

Figure 6. Output Enable Generator and I/O Cell

MACH 5 TIMING MODEL

The primary focus of the MACH 5 timing model is to accurately represent the timing in a MACH 5 device, and at the same time, be easy to understand. This model accurately describes all combinatorial and registered paths through the device, making a distinction between **internal feedback** and **external feedback**. A signal uses internal feedback when it is fed back into the switch matrix or block without having to go through the output buffer. The input register specifications are also reported as internal feedback. When a signal is fed back into the switch matrix after having gone through the output buffer, it is using external feedback.

The parameter, t_{BUF}, is defined as the time it takes to go through the output buffer to the I/O pad. If a signal goes to the internal feedback rather than to the I/O pad, the parameter designator is followed by an "i". By adding t_{BUF} to this internal parameter, the external parameter is derived. For example, $t_{PD} = t_{PDi} + t_{BUF}$. A diagram representing the modularized MACH 5 timing model is shown in Figure 7. Refer to the Technical Note entitled *MACH 5 Timing and High Speed Design* for a more detailed discussion about the timing parameters.

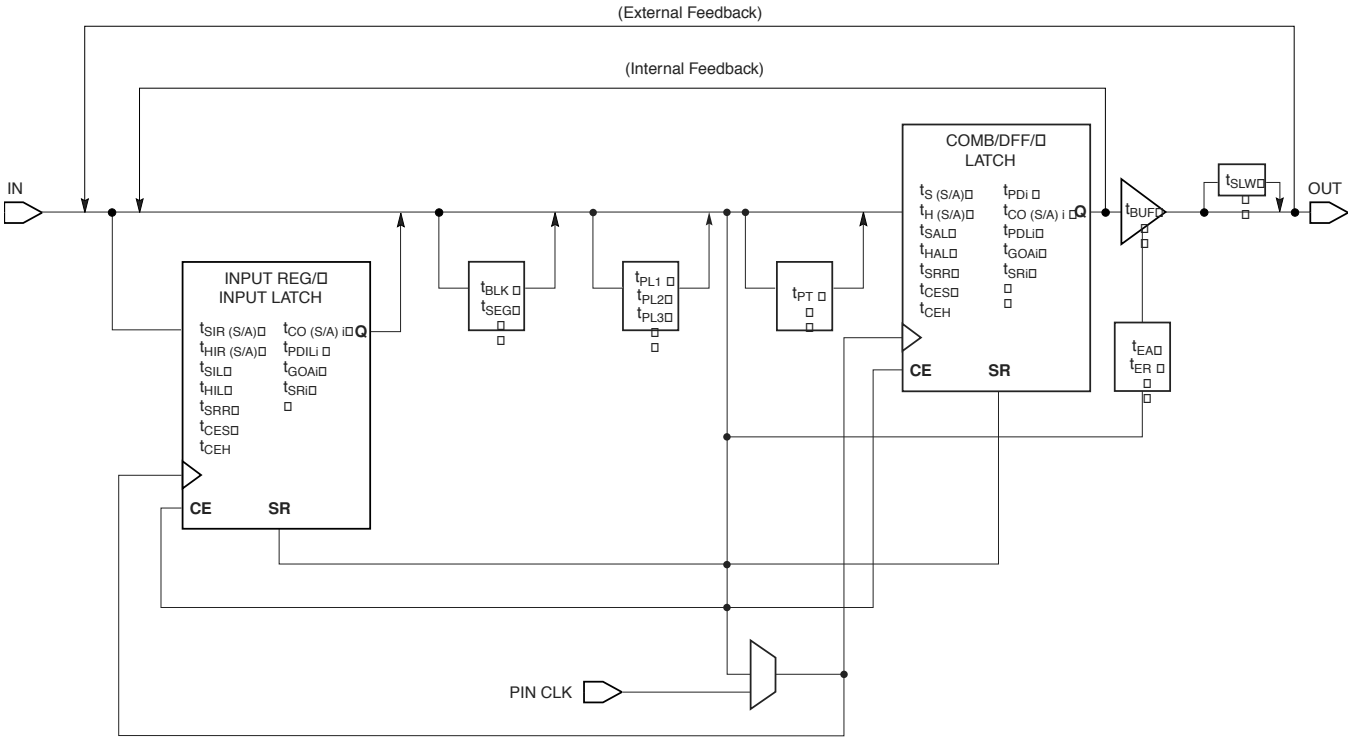


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Figure 7. MACH 5 Timing Model

SAFE FOR MIXED SUPPLY VOLTAGE SYSTEM DESIGNS [1]

Both the 3.3-V and 5-V V_{CC} MACH 5 devices are safe for mixed supply voltage system designs. The 5-V devices will not overdrive 3.3-V devices above the output voltage of 3.3 V, while they accept inputs from other 3.3-V devices. The 3.3-V devices will accept inputs up to 5.5 V. Both the 3.3-V and 5-V versions have the same high-speed performance and provide easy-to-use mixed-voltage design capability.

Note:

1. *Excludes original M5-128, M5-192, and M5-256 while M5-128/1, M3-192/1 and M5-256/1 are supported. Please refer to Application Note titled "Hot Socketing and Mixed Supply Design with MACH 4 and MACH 5 Devices".*

BUS-FRIENDLY INPUTS AND I/OS

All MACH 5 devices have inputs and I/Os which feature the Bus-Friendly circuitry incorporating two inverters in series which loop back to the input. This double inversion weakly holds the input at its last driven logic state. While it is a good design practice to tie unused pins to a known state, the Bus-Friendly input structure pulls pins away from the input threshold voltage where noise can cause high-frequency switching. At power-up, the Bus-Friendly latches are reset to a logic level "1." For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

POWER MANAGEMENT

There are 4 power/speed options in each MACH 5 PAL block (Table 5). The speed and power tradeoff can be tailored for each design. The signal speed paths in the lower-power PAL blocks will be slower than those in the higher-power PAL blocks. This feature allows speed critical paths to run at maximum frequency while the rest of the signal paths operate in a lower-power mode. In large designs, there may be several different speed requirements for different portions of the design.

Table 5. Power Levels

High Speed/High Power	100% Power
Medium High Speed/Medium High Power	67% Power
Medium Low Speed/Medium Low Power	40% Power
Low Speed/Low Power	20% Power

PROGRAMMABLE SLEW RATE

Each MACH 5 device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for the higher speed transition (3 V/ns) or for the lower noise transition (1 V/ns). For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise, and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed. The slew rate is adjusted independent of power.

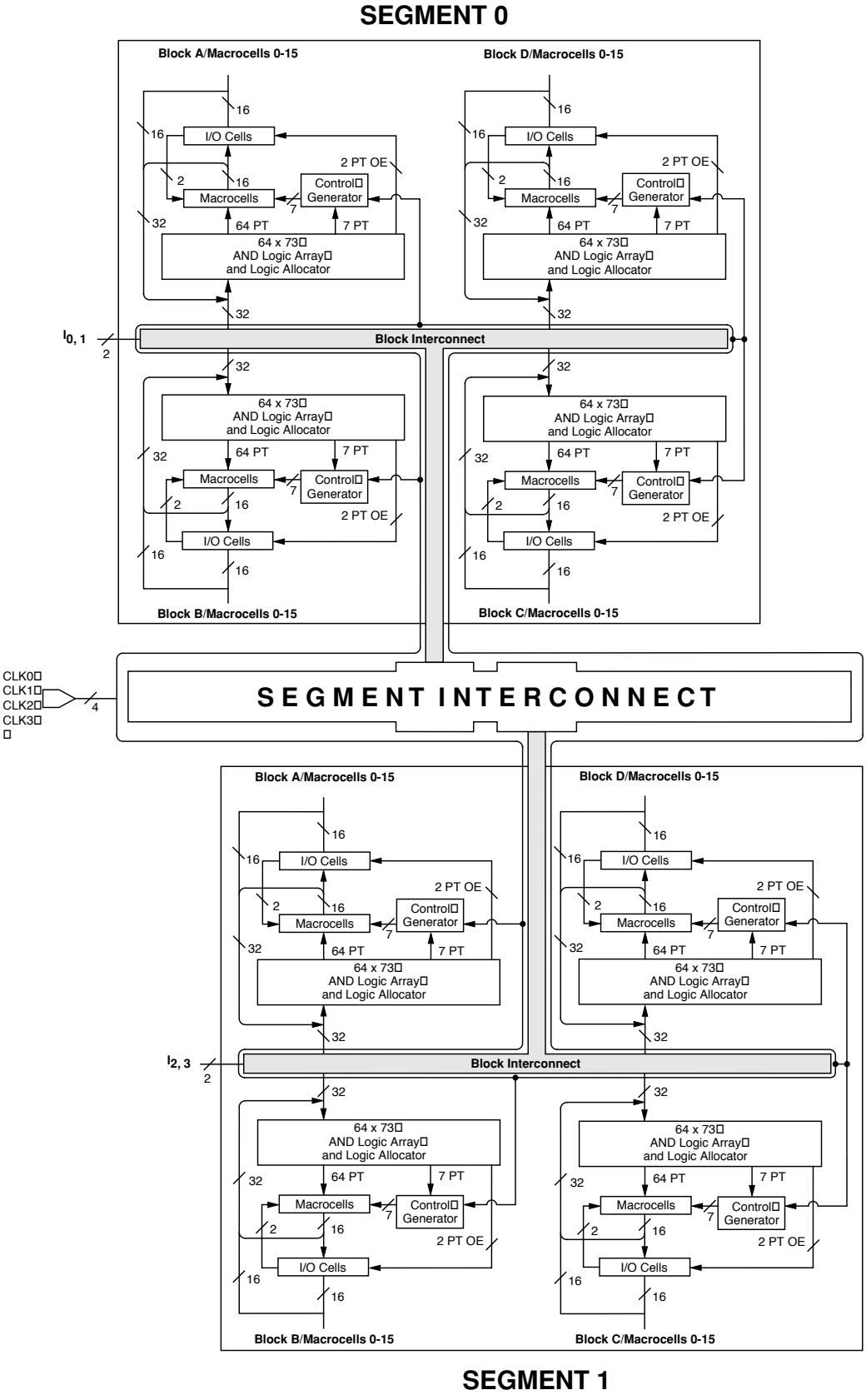
POWER-UP RESET/SET

All flip-flops power up to a known state for predictable system initialization. If a macrocell is configured to SET on a signal from the control generator, then that macrocell will be SET during device power-up. If a macrocell is configured to RESET on a signal from the control generator or is not configured for set/reset, then that macrocell will RESET on power-up. To guarantee initialization values, the V_{CC} rise must be monotonic and the clock must be inactive until the reset delay time has elapsed.

SECURITY BIT

A programmable security bit is provided on the MACH 5 devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

BLOCK DIAGRAM — M5(LV)-128/XXX



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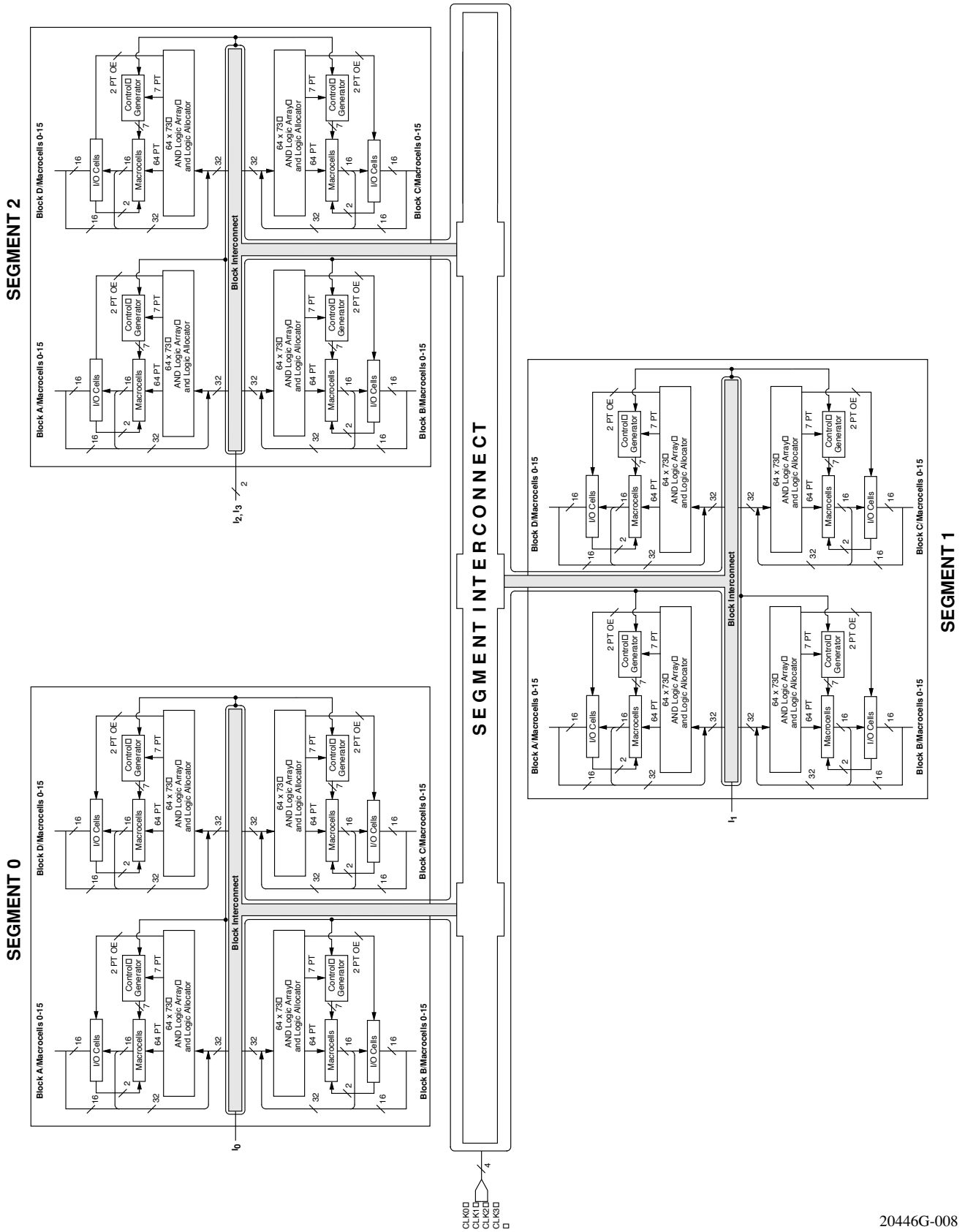
Select devices have been discontinued.
See Ordering Information section for product status.

BLOCK DIAGRAM — M5-192/XXX



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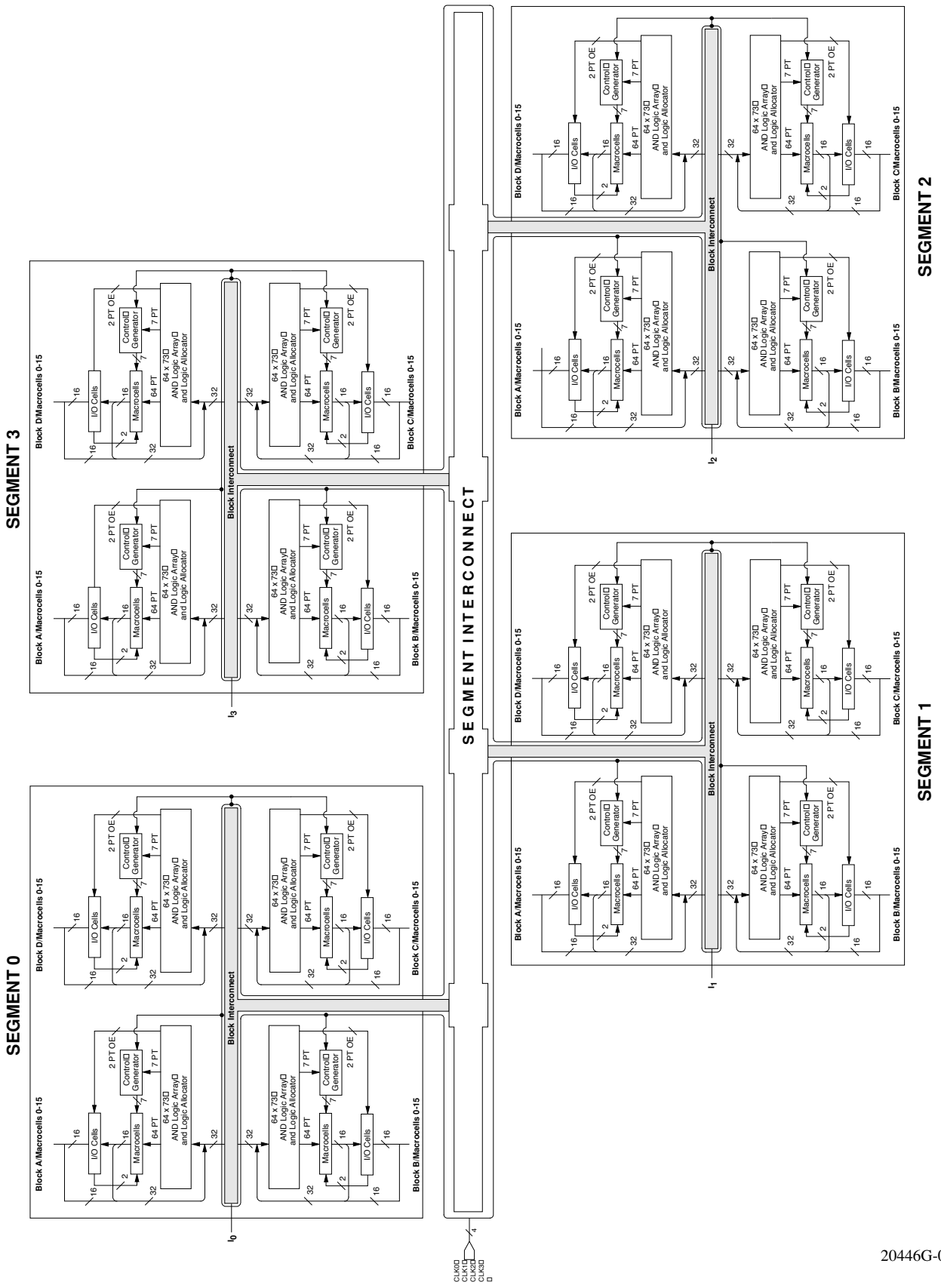
Select devices have been discontinued.
See Ordering Information section for product status.

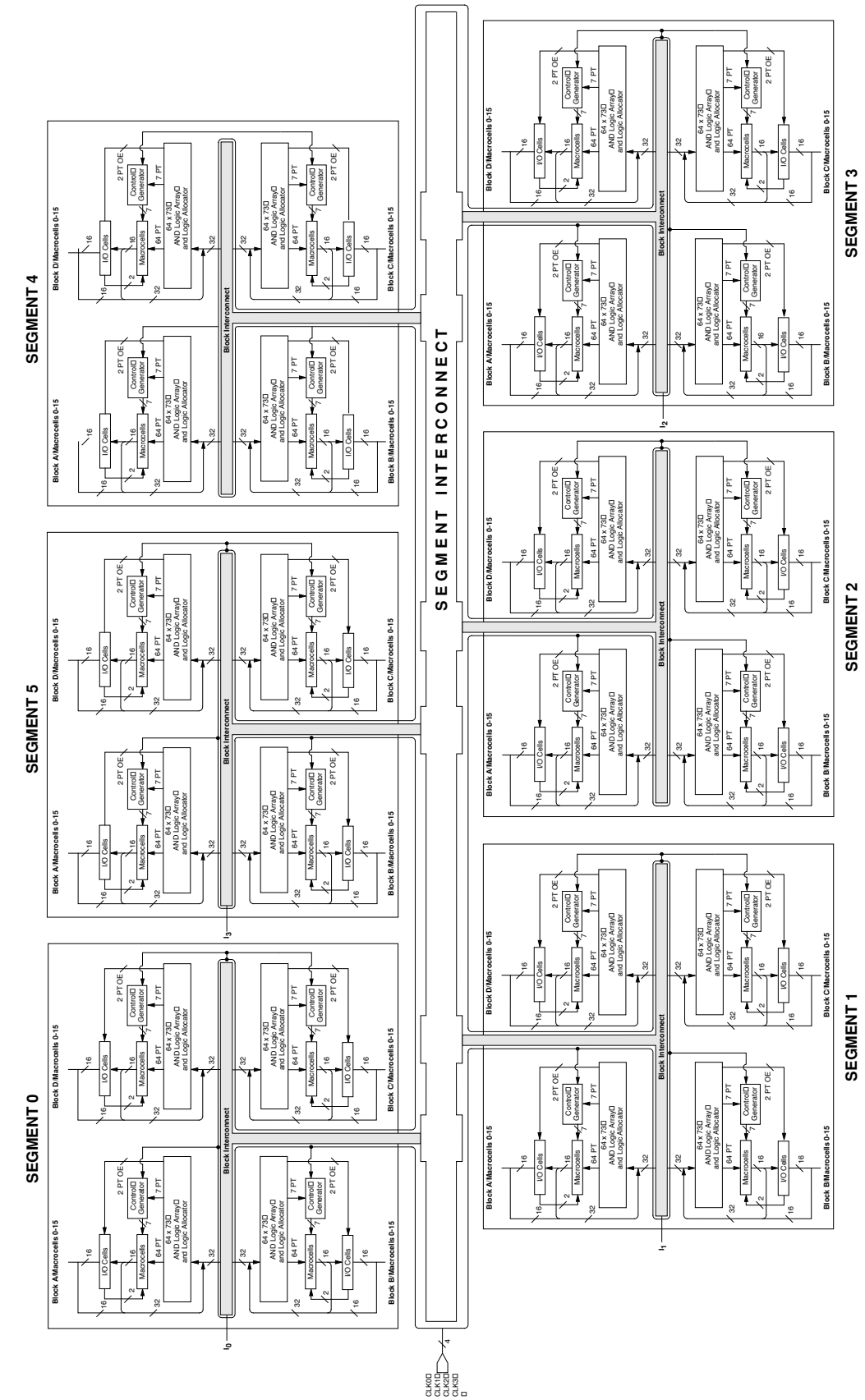
BLOCK DIAGRAM — M5(LV)-256/XXX



20446G-009

Select devices have been discontinued.
See Ordering Information section for product status.

BLOCK DIAGRAM — M5(LV)-384/XXX



20446G-011

Select devices have been discontinued.
See Ordering Information section for product status.

M5(LV) TIMING PARAMETERS OVER OPERATING RANGES[1] (CONTINUED)

		-5		-6		-7		-10		-12		-15		-20		
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit
Power Delays:																
t_{PL1}	Power level 1 delay (Note 2)		4.0 (5.0)		4.0		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)	ns
t_{PL2}	Power level 2 delay (Note 2)		6.0 (9.0)		6.0		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)	ns
t_{PL3}	Power level 3 delay (Note 2)		9.0 (17.5)		9.0		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)	ns
Additional Cluster Delay:																
t_{PT}	Product term cluster delay		0.3		0.3		0.3		0.3		0.3		0.3		0.3	ns
Interconnect Delays:																
t_{BLK}	Block interconnect delay		1.5		1.5		1.5		2.0		2.0		2.0		2.0	ns
t_{SEG}	Segment interconnect delay		4.5		4.5		5.0		6.0		6.0		6.0		6.0	ns
Reset and Preset Delays:																
t_{SRi}	Asynchronous reset or preset to internal register output		6.0		8.0		8.0		10.0		12.0		14.0		16.0	ns
t_{SR}	Asynchronous reset or preset to register output		8.0		10.0		10.0		12.0		14.0		16.0		18.0	ns
t_{SRR}	Reset and set register recovery time	5.5		7.5		7.5		8.0		9.0		10.0		11.0		ns
t_{SRW}	Asynchronous reset or preset width	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
Clock Enable Delays:																
t_{CES}	Clock enable setup time	4.0		5.0		5.0		6.0		7.0		7.0		8.0		ns
t_{CEH}	Clock enable hold time	3.0		4.0		4.0		5.0		6.0		6.0		7.0		ns
Width:																
t_{WLS}	Global clock width low (Note 3)	2.5		3.0		3.0		4.0		5.0		6.0		6.0		ns
t_{WHS}	Global clock width high (Note 3)	2.5		3.0		3.0		4.0		5.0		6.0		6.0		ns
t_{WLA}	Product term clock width low	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t_{WHA}	Product term clock width high	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t_{GWA}	Gate width low (for low transparent) or high (for high transparent)	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t_{WIR}	Input register clock width low or high	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns

M5(LV) TIMING PARAMETERS OVER OPERATING RANGES[1] (CONTINUED)

		-5		-6		-7		-10		-12		-15		-20		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Frequency:																
f_{MAX}	External feedback, PAL block level. Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SS} + t_{COS})$	133		125		100		83.3		71.4		55.6		45.5		MHz
	Internal feedback, PAL block level. Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SS} + t_{COSi})$	182		167		125		100		83.3		62.5		50.0		MHz
	No feedback PAL block level. Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SS} + t_{HS})$	200		167		167		125		100		83.3		83.3		MHz
f_{MAXA}	External feedback, PAL block level. Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SA} + t_{COA})$	91		91		71.4		58.8		47.6		41.7		35.7		MHz
	Internal feedback, PAL block level. Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SA} + t_{COAi})$	111		111		83.3		66.7		52.6		45.5		38.5		MHz
	No feedback, PAL block level. Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SA} + t_{HA})$	167		125		125		100		83.3		71.4		62.5		MHz
f_{MAXI}	Maximum input register frequency $1/(t_{SIRS}+t_{HIRS})$ or $1/(2 \times t_{WICW})$	167		125		125		100		83.3		71.4		62.5		MHz

Notes:

1. *See "MACH Switching Test Circuits" documentation on the Lattice Data Book CD-ROM or Lattice web site.*
2. *Numbers in parentheses are for M5-128, M5-192, M5-256.*
3. *If a signal is used as both a clock and a logic array input, then the maximum input frequency applies ($f_{MAX}/2$).*

CAPACITANCE[1]

Parameter Symbol	Parameter Description	Test conditions		Typ	Unit
C_{IN}	I/CLK pin	V_{IN} =2.0 V	3.3 V or 5 V, 25° C, 1 MHz	12	pF
$C_{I/O}$	I/O pin	V_{OUT} =2.0 V	3.3 V or 5 V, 25° C, 1 MHz	10	pF

1. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where these parameters may be affected.

I_{CC} vs. FREQUENCY

These curves represent the typical power consumption for a particular device at system frequency. The selected "typical" pattern is a 16-bit up-down counter. This pattern fills the device and exercises every macrocell. Maximum frequency shown uses internal feedback and a D-type register. Power/Speed are optimized to obtain the highest counter frequency and the lowest power. The highest frequency (LSBs) is placed in common PAL blocks, which are set to high power. The lowest frequency signals (MSBs) are placed in a common PAL block and set to lowest power. For a more detailed discussion about MACH 5 power consumption, refer to the application note entitled *MACH 5 Power* in the Application Notes section on the Lattice Data Book CD-ROM or Lattice web site.

I_{CC} CURVES AT HIGH /LOW POWER MODES

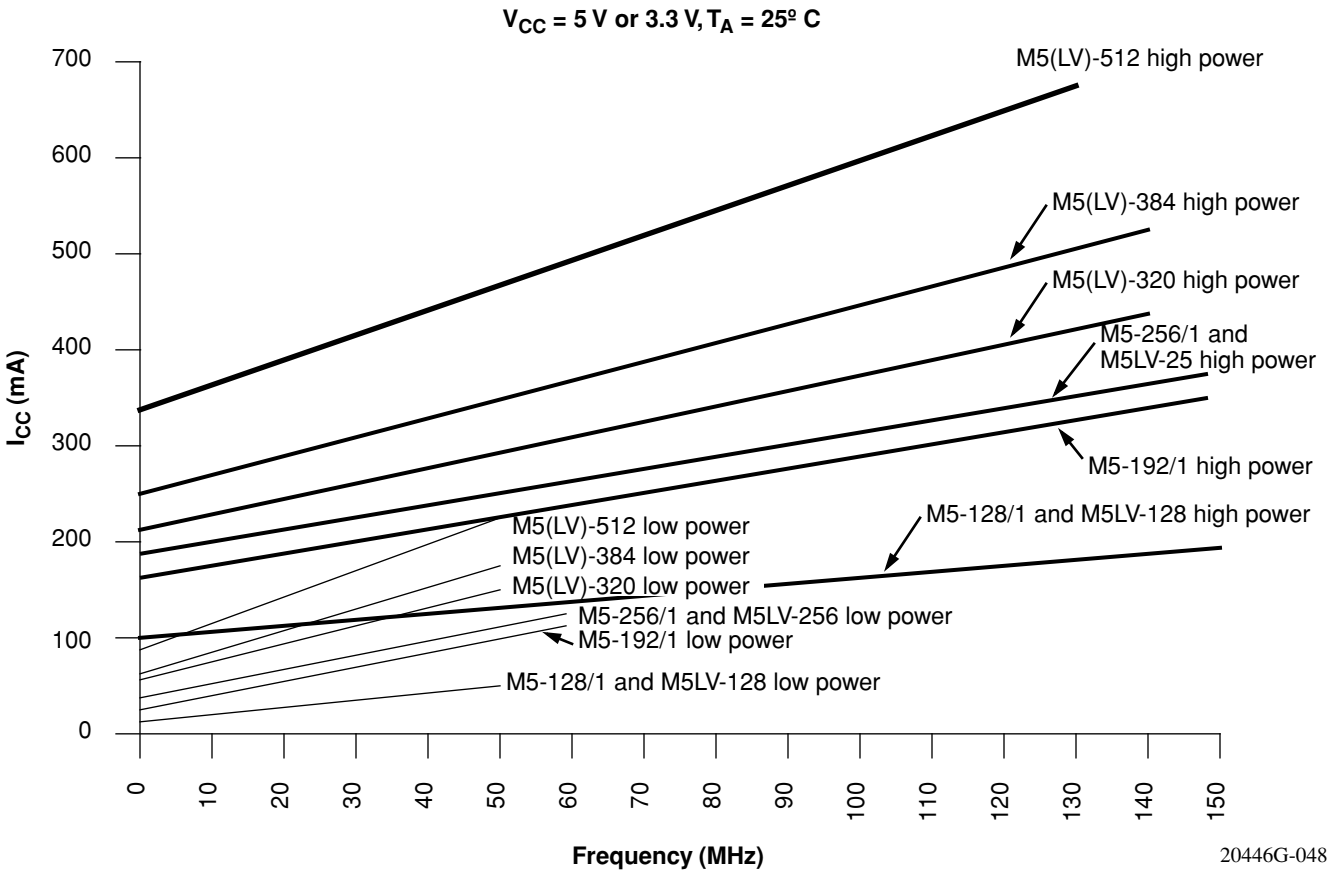
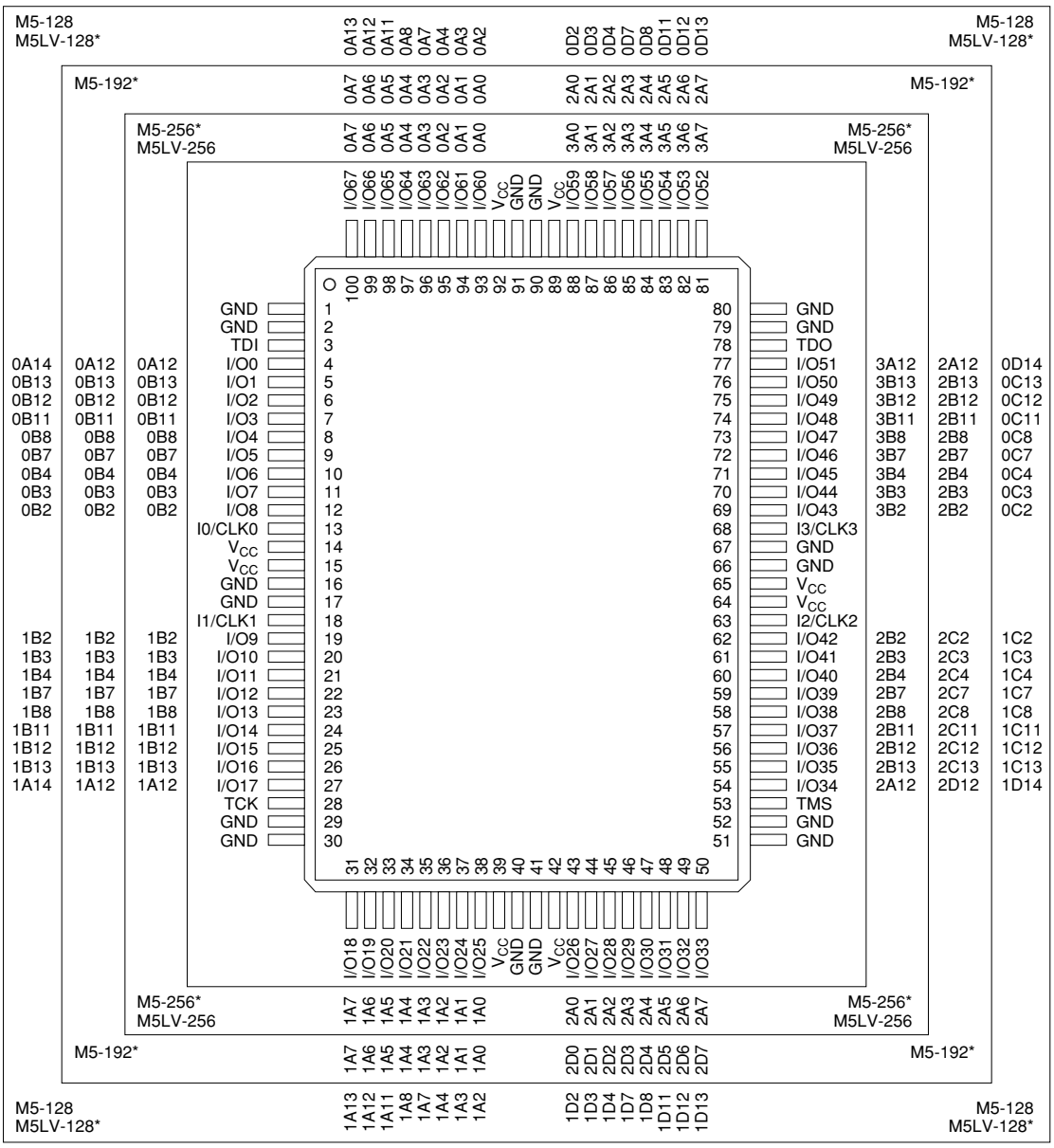


Figure 8. I_{CC} Curves at High/Low Power Modes

100-PIN PQFP CONNECTION DIAGRAM

Top View

100-Pin PQFP (68 I/O)



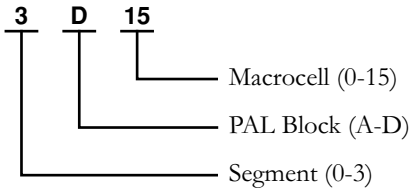
*Package obsolete, contact factory.

20446G-016

Select devices have been discontinued. See Ordering Information section for product status.

Pin Designations

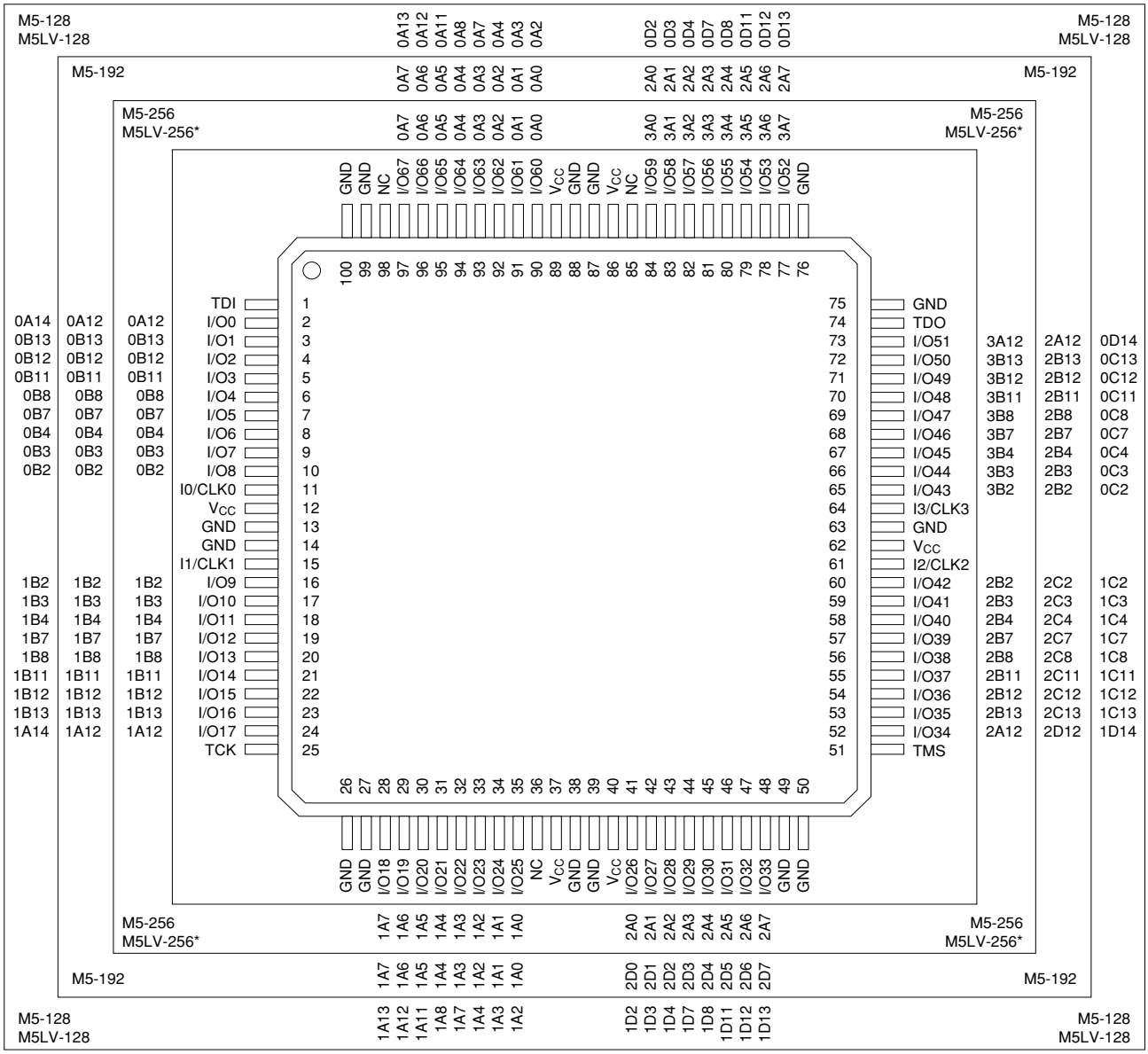
CLK	=	Clock	V_{CC}	=	Supply Voltage
GND	=	Ground	TDI	=	Test Data In
I	=	Input	TCK	=	Test Clock
I/O	=	Input/Output	TMS	=	Test Mode Select
NC	=	No Connect	TDO	=	Test Data Out



100-PIN TQFP CONNECTION DIAGRAM – 68 I/O

Top View

100-Pin TQFP (68 I/O)

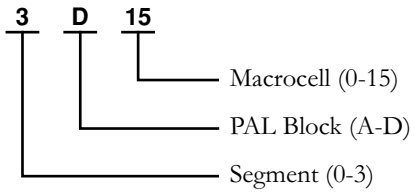


*Package obsolete, contact factory.

20446G-017

Pin Designations

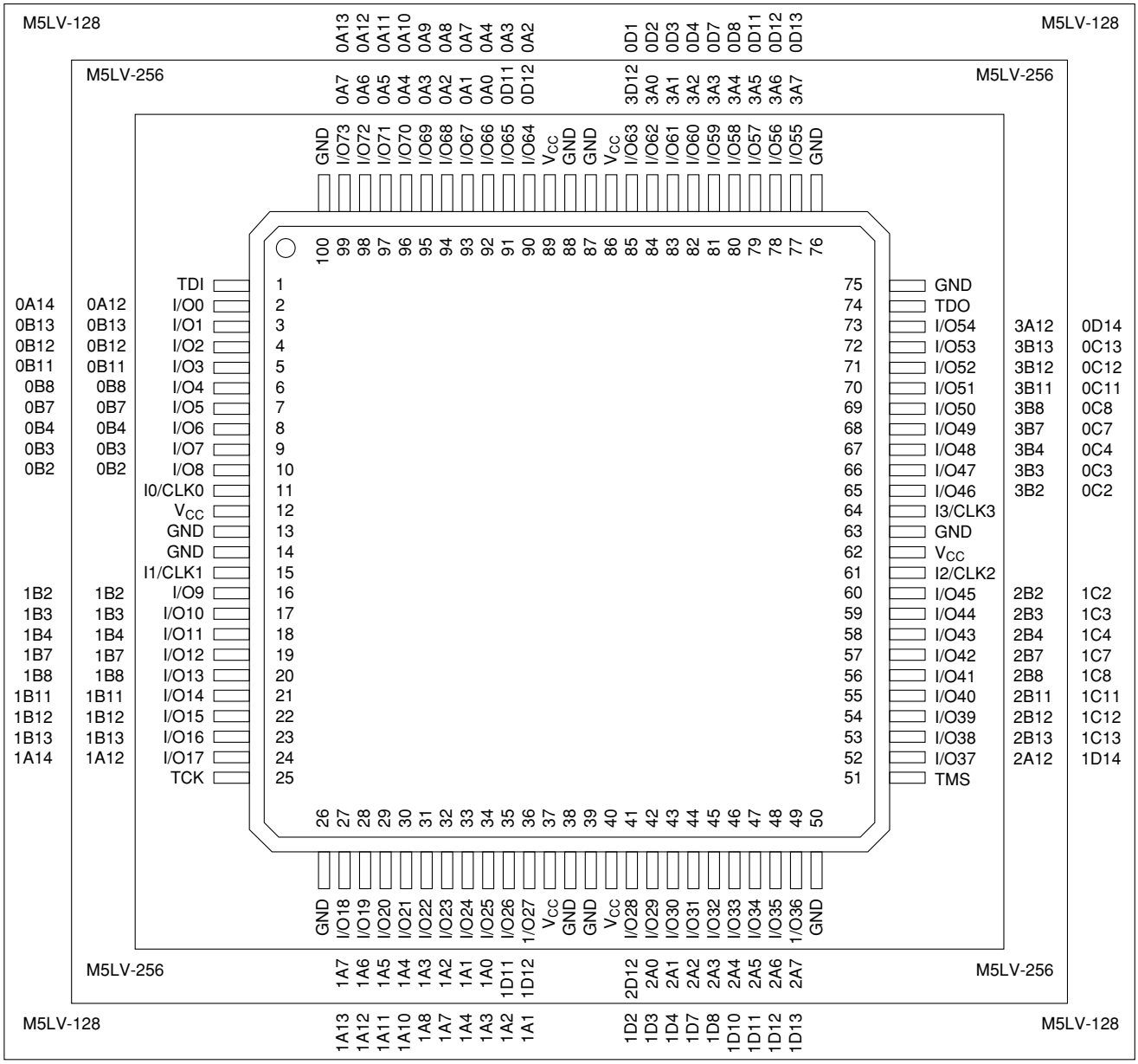
CLK	=	Clock	V_{CC}	=	Supply Voltage
GND	=	Ground	TDI	=	Test Data In
I	=	Input	TCK	=	Test Clock
I/O	=	Input/Output	TMS	=	Test Mode Select
NC	=	No Connect	TDO	=	Test Data Out



100-PIN TQFP CONNECTION DIAGRAM – 74 I/O

Top View

100-Pin TQFP (74 I/O)

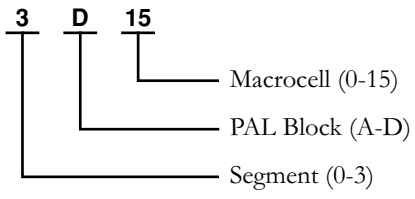


20446G-018

Select devices have been discontinued. See Ordering Information section for product status.

Pin Designations

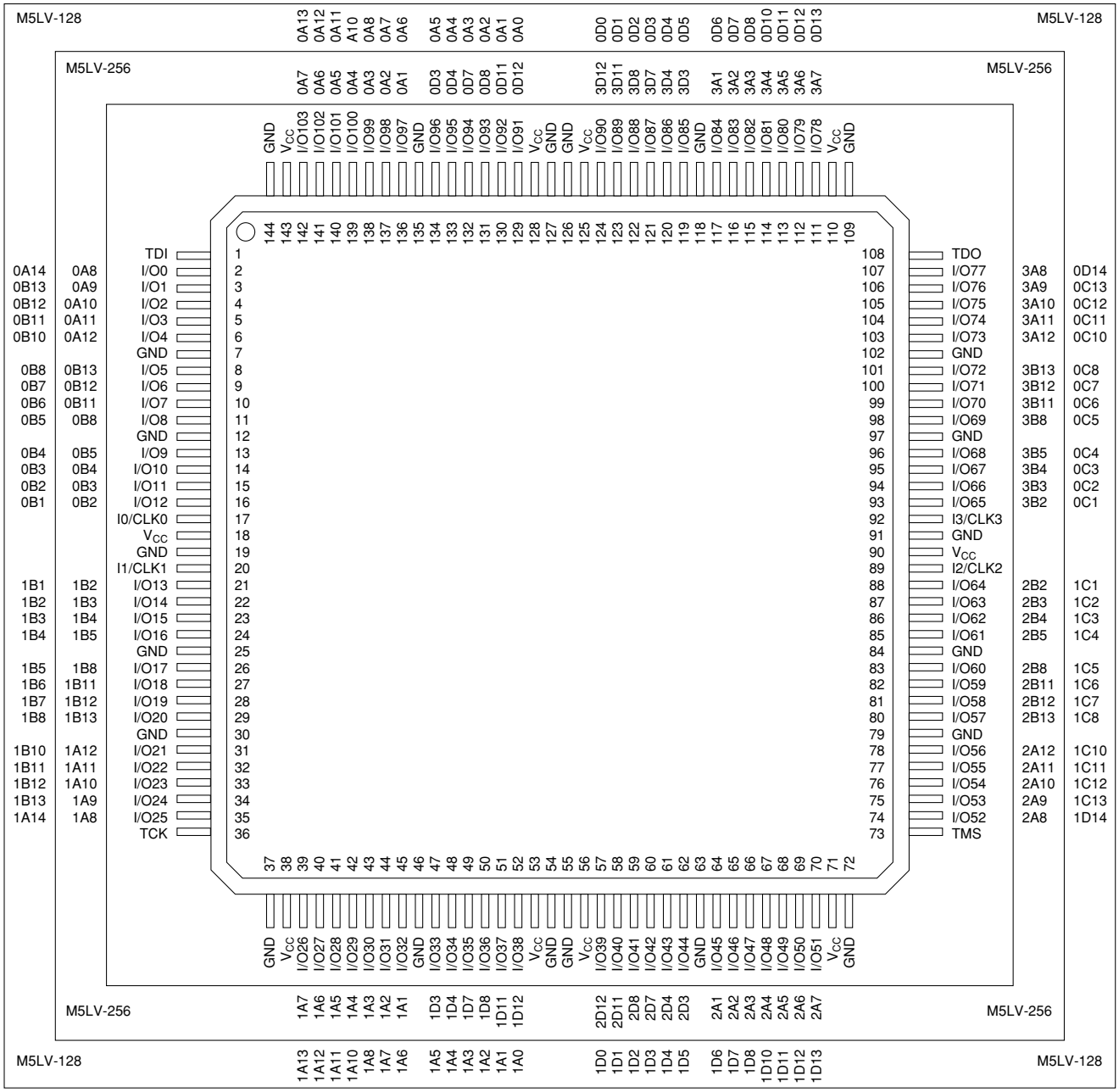
CLK	=	Clock	V_{CC}	=	Supply Voltage		
GND	=	Ground	TDI	=	Test Data In		
I	=	Input	TCK	=	Test Clock		
I/O	=	Input/Output	TMS	=	Test Mode Select		
NC	=	No Connect	TDO	=	Test Data Out		



144-PIN TQFP CONNECTION DIAGRAM

Top View

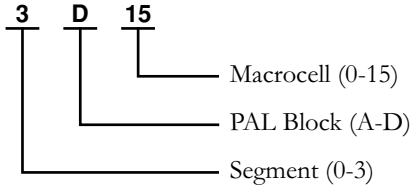
144-Pin TQFP



20446G-020

Pin Designations

CLK	=	Clock	V_{CC}	=	Supply Voltage
GND	=	Ground	TDI	=	Test Data In
I	=	Input	TCK	=	Test Clock
I/O	=	Input/Output	TMS	=	Test Mode Select
NC	=	No Connect	TDO	=	Test Data Out

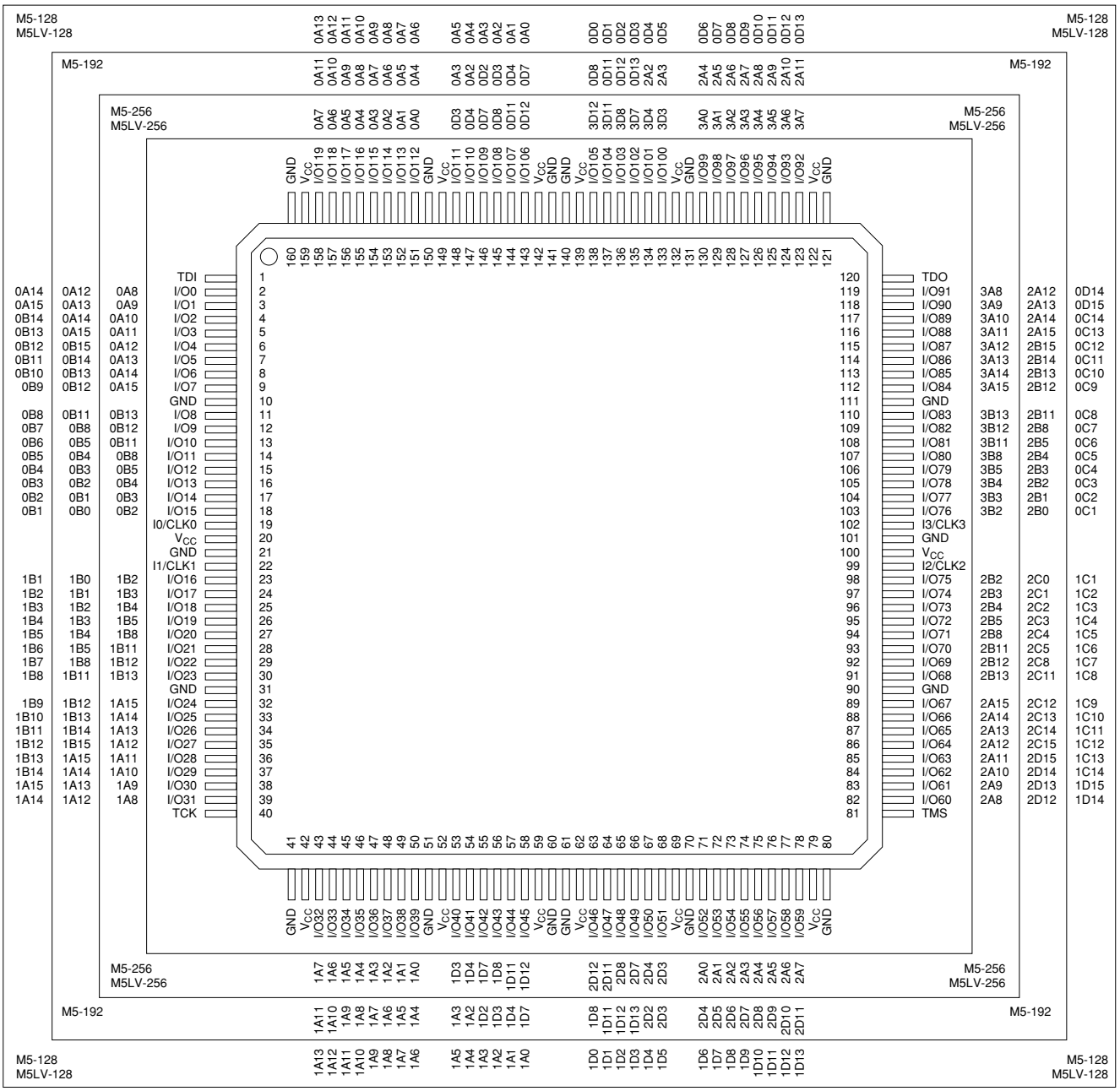


Select devices have been discontinued. See Ordering Information section for product status.

160-PIN PQFP CONNECTION DIAGRAM

Top View

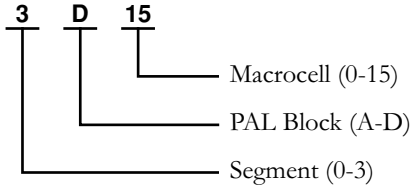
160-Pin PQFP (128, 192, 256 Macrocells)



20446G-021

Pin Designations

CLK	=	Clock	V_{CC}	=	Supply Voltage
GND	=	Ground	TDI	=	Test Data In
I	=	Input	TCK	=	Test Clock
I/O	=	Input/Output	TMS	=	Test Mode Select
NC	=	No Connect	TDO	=	Test Data Out



Select devices have been discontinued. See Ordering Information section for product status.

256-BALL BGA CONNECTION DIAGRAM — M5-320

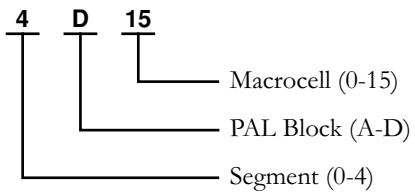
Bottom View (Macrocell Association)

256-Ball BGA

	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	T	U	V	W	Y	
1	GND	GND	3A11	3D15	3D12	GND	3D7	GND	3D3	3D2	GND	2D2	GND	2D7	GND	2D10	2D13	2D15	GND	GND	1
2	GND	3B2	3A3	3A8	3A13	3D13	3D9	3D8	3D4	I3/CLK3	I2/CLK2	2D3	2D4	2D8	2D12	2A15	2A13	2A12	2A9	2A7	2
3	GND	3B8	V_{CC}	3A2	3A4	3A12	3D14	3D10	3D5	3D0	2D0	2D5	2D9	2D14	2A14	2A10	2A8	V_{CC}	2A3	GND	3
4	3B13	3B11	3B3	V_{CC}	TDO	3A7	V_{CC}	3D11	3D6	3D1	2D1	2D6	2D11	V_{CC}	2A11	TMS	V_{CC}	2A6	2A2	2A0	4
5	4B14	4B15	3B4	V_{CC}													V_{CC}	2A5	2B0	2B1	5
6	GND	4B11	3B12	3B7													2A4	2A1	2B4	GND	6
7	4B8	4B10	4B13	V_{CC}													V_{CC}	2B2	2B5	2B7	7
8	4B4	4B6	4B9	4B12													2B3	2B6	2B9	2B11	8
9	GND	4B3	4B5	4B7													2B8	2B10	2B12	GND	9
10	GND	4B0	4B1	4B2													2B13	2B14	2B15	GND	10
11	GND	4A0	4A1	4A2													1B13	1B14	1B15	GND	11
12	GND	4A3	4A5	4A7													1B8	1B10	1B12	GND	12
13	4A4	4A6	4A9	4A12													1B3	1B6	1B9	1B11	13
14	4A8	4A10	4A13	V_{CC}													V_{CC}	1B2	1B5	1B7	14
15	GND	4A11	0B12	0B7													1A4	1A1	1B4	GND	15
16	4A14	4A15	0B4	V_{CC}													V_{CC}	1A5	1B0	1B1	16
17	0B13	0B11	0B3	V_{CC}	TDI	0A7	V_{CC}	0D11	0D6	0D1	1D1	1D6	1D11	V_{CC}	1A11	TCK	V_{CC}	1A6	1A2	1A0	17
18	GND	0B8	V_{CC}	0A2	0A4	0A12	0D14	0D9	0D5	0D0	1D0	1D5	1D10	1D14	1A14	1A10	1A8	V_{CC}	1A3	GND	18
19	0B2	0A3	0A8	0A11	0A13	0D12	0D8	0D4	0D3	I0/CLK0	I1/CLK1	1D4	1D8	1D9	1D13	1A15	1A12	1A9	1A7	GND	19
20	GND	GND	0D15	0D13	0D10	GND	0D7	GND	0D2	GND	1D2	1D3	GND	1D7	GND	1D12	1D15	1A13	GND	GND	20
	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	T	U	V	W	Y	

Pin Designations

CLK	=	Clock
GND	=	Ground
I	=	Input
I/O	=	Input/Output
NC	=	No Connect
V_{CC}	=	Supply Voltage
TDI	=	Test Data In
TCK	=	Test Clock
TMS	=	Test Mode Select
TDO	=	Test Data Out



20446G-029

Select devices have been discontinued. See Ordering Information section for product status.

352-BALL BGA CONNECTION DIAGRAM — M5-512, M5LV-512

Bottom View (I/O Pin-outs)

352-Ball BGA

	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	T	U	V	W	Y	AA	AB	AC	AD	AE	AF	
1	NC	NC	NC	GND	NC	I/O245	GND	I/O246	I/O247	GND	I/O248	I/O249	I3/CLK3	GND	I/O250	I/O251	I/O252	GND	I/O253	I/O254	GND	NC	I/O255	GND	NC	NC	1
2	NC	NC	NC	I/O224	I/O225	I/O226	I/O227	I/O228	I/O229	I/O230	I/O231	I/O232	I/O233	I2CLK2	I/O235	I/O236	I/O237	I/O238	I/O239	I/O240	I/O241	I/O242	I/O243	I/O244	GND	GND	2
3	GND	GND	NC	I/O205	I/O206	I/O207	I/O208	I/O209	I/O210	I/O211	I/O212	I/O213	I/O214	I2CLK2	I/O215	I/O216	I/O217	I/O218	I/O219	I/O220	I/O221	I/O222	I/O223	TMS	NC	NC	3
4	NC	I/O188	NC	TDO	I/O189	I/O190	I/O191	V_{CC}	I/O192	V_{CC}	I/O193	I/O194	I/O195	V_{CC}	I/O196	I/O197	I/O198	V_{CC}	I/O199	V_{CC}	I/O200	I/O201	V_{CC}	I/O202	I/O203	I/O204	4
5	GND	I/O183	I/O184	V_{CC}																			I/O185	I/O186	I/O187	GND	5
6	NC	I/O176	I/O177	I/O178																			I/O179	I/O180	I/O181	I/O182	6
7	GND	I/O169	I/O170	I/O171																			I/O172	I/O173	I/O174	I/O175	7
8	I/O162	I/O163	I/O164	I/O165																			I/O166	I/O167	I/O168	NC	8
9	I/O156	I/O157	I/O158	I/O159																			V_{CC}	I/O160	I/O161	GND	9
10	GND	I/O150	I/O151	V_{CC}																			I/O152	I/O153	I/O154	I/O155	10
11	I/O142	I/O143	I/O144	I/O145																			I/O146	I/O147	I/O148	I/O149	11
12	I/O134	I/O135	I/O136	I/O137																			I/O138	I/O139	I/O140	I/O141	12
13	I/O128	I/O129	I/O130	I/O131																			V_{CC}	I/O132	I/O133	GND	13
14	GND	I/O122	I/O123	V_{CC}																			I/O124	I/O125	I/O126	I/O127	14
15	I/O114	I/O115	I/O116	I/O117																			I/O118	I/O119	I/O120	I/O121	15
16	NC	I/O107	I/O108	I/O109																			I/O110	I/O111	I/O112	I/O113	16
17	I/O101	I/O102	I/O103	I/O104																			V_{CC}	I/O105	I/O106	GND	17
18	GND	I/O95	I/O96	V_{CC}																			I/O97	I/O98	I/O99	I/O100	18
19	I/O87	I/O88	I/O89	I/O90																			I/O91	I/O92	I/O93	I/O94	19
20	I/O80	I/O81	I/O82	I/O83																			I/O84	I/O85	I/O86	GND	20
21	I/O73	I/O74	I/O75	I/O76																			I/O77	I/O78	I/O79	NC	21
22	GND	I/O68	I/O69	I/O70																			V_{CC}	I/O71	I/O72	GND	22
23	I/O51	I/O52	I/O53	V_{CC}	I/O54	I/O55	V_{CC}	I/O56	V_{CC}	I/O57	I/O58	I/O59	V_{CC}	I/O60	I/O61	I/O62	V_{CC}	I/O63	V_{CC}	I/O64	I/O65	I/O66	TCK	NC	I/O67	NC	23
24	NC	NC	TDI	I/O32	I/O33	I/O34	I/O35	I/O36	I/O37	I/O38	I/O39	I/O40	I0/CLK0	I/O41	I/O42	I/O43	I/O44	I/O45	I/O46	I/O47	I/O48	I/O49	I/O50	NC	GND	GND	24
25	GND	GND	I/O11	I/O12	I/O13	I/O14	I/O15	I/O16	I/O17	I/O18	I/O19	I/O20	I/O21	I/O22	I/O23	I/O24	I/O25	I/O26	I/O27	I/O28	I/O29	I/O30	I/O31	NC	NC	NC	25
26	NC	NC	GND	I/O0	NC	GND	I/O1	I/O2	GND	I/O3	I/O4	I/O5	GND	I1/CLK1	I/O6	I/O7	GND	I/O8	I/O9	GND	I/O10	NC	GND	NC	NC	NC	26
	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	T	U	V	W	Y	AA	AB	AC	AD	AE	AF	

20446G-030

Pin Designations

CLK	=	Clock
GND	=	Ground
I	=	Input
I/O	=	Input/Output
NC	=	No Connect
V_{CC}	=	Supply Voltage
TDI	=	Test Data In
TCK	=	Test Clock
TMS	=	Test Mode Select
TDO	=	Test Data Out

Select devices have been discontinued.
See Ordering Information section for product status.